

1.4MHz, Rail-to-Rail I/O CMOS Operational Amplifier

1 FEATURES

- **HIGH GAIN BANDWIDTH:1.4MHz**
- **RAIL-TO-RAIL INPUT AND OUTPUT**
±0.1mV Typical Vos
- **INPUT VOLTAGE RANGE: -0.1V to +5.6V**
with Vs = 5.5V
- **SUPPLY RANGE: +2.2V to +5.5V**
- **SPECIFIED UP TO +125°C**
- **Micro SIZE PACKAGES: SOT23-5, SOIC-8**

2 APPLICATIONS

- **SENSORS**
- **PHOTODIODE AMPLIFICATION**
- **ACTIVE FILTERS**
- **TEST EQUIPMENT**
- **DRIVING A/D CONVERTERS**

3 DESCRIPTIONS

The RS6331P, RS6332P, RS6334P families of products offer low voltage operation and rail-to-rail input and output, as well as excellent speed/power consumption ratio, providing an excellent bandwidth (1.4MHz) and slew rate of 0.5V/us. The op-amps are unity gain stable and feature an ultra-low input bias current.

The devices are ideal for sensor interfaces, active filters, and portable applications. The RS6331P, RS6332P, RS6334P families of operational amplifiers are specified at the full temperature range of -40°C to +125°C under single or dual power supplies of 2.2V to 5.5V.

Device Information⁽¹⁾

PART NUMBER	PACKAGE	BODY SIZE(NOM)
RS6331P	SOT23-5	2.90mm×1.60mm
	SOIC-8(SOP8)	4.90mm×3.90mm
	MSOP-8	3.00mm×3.00mm
	SOT353 (SC70-5)	2.10mm×1.25mm
RS6332P	SOIC-8(SOP8)	4.90mm×3.90mm
	MSOP-8	3.00mm×3.00mm
	TSSOP-8	3.00mm×4.40mm
	DFN2×2-8L	2.00mm×2.00mm
RS6334P	SOIC-14 (SOP14)	8.65mm×3.90mm
	TSSOP-14	5.00mm×4.40mm

(1) For all available packages, see the orderable addendum at the end of the data sheet.

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4 Revision History

Note: Page numbers for previous revisions may differ from page numbers in the current version.

Version	Change Date	Change Item
D.1	2022/08/10	Version Updated
D.2	2023/09/21	Added Thermal Pad Pin Description

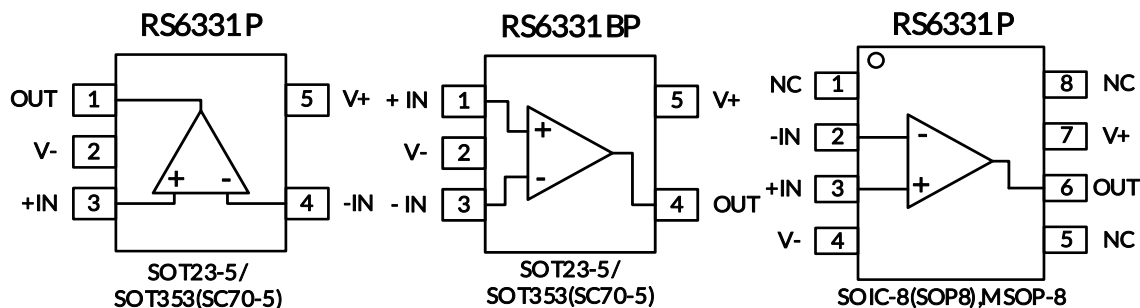
5 PACKAGE/ORDERING INFORMATION (1)

Orderable Device	Package Type	Pin	Channel	Op Temp(°C)	Device Marking (2)	Package Qty
RS6331PXF	SOT23-5	5	1	-40°C ~125°C	6331P	Tape and Reel,3000
RS6331PXC5	SOT353(SC70-5)	5	1	-40°C ~125°C	6331P	Tape and Reel,3000
RS6331BPXF	SOT23-5	5	1	-40°C ~125°C	6331BP	Tape and Reel,3000
RS6331BPXC5	SOT353(SC70-5)	5	1	-40°C ~125°C	6331BP	Tape and Reel,3000
RS6332P XK	SOIC-8(SOP8)	8	2	-40°C ~125°C	RS6332P	Tape and Reel,4000
RS6332PXM	MSOP-8	8	2	-40°C ~125°C	RS6332P	Tape and Reel,4000
RS6332PXQ	TSSOP-8	8	2	-40°C ~125°C	RS6332P	Tape and Reel,4000
RS6334PXP	SOIC-14(SOP14)	14	4	-40°C ~125°C	RS6334P	Tape and Reel,4000
RS6334PXQ	TSSOP-14	14	4	-40°C ~125°C	RS6334P	Tape and Reel,4000

NOTE:

- (1) This information is the most current data available for the designated devices. This data is subject to change without notice and revision of this document. For browser-based versions of this data sheet, refer to the right-hand navigation.
- (2) There may be additional marking, which relates to the lot trace code information (data code and vendor code), the logo or the environmental category on the device.

6 Pin Configuration and Functions (Top View)

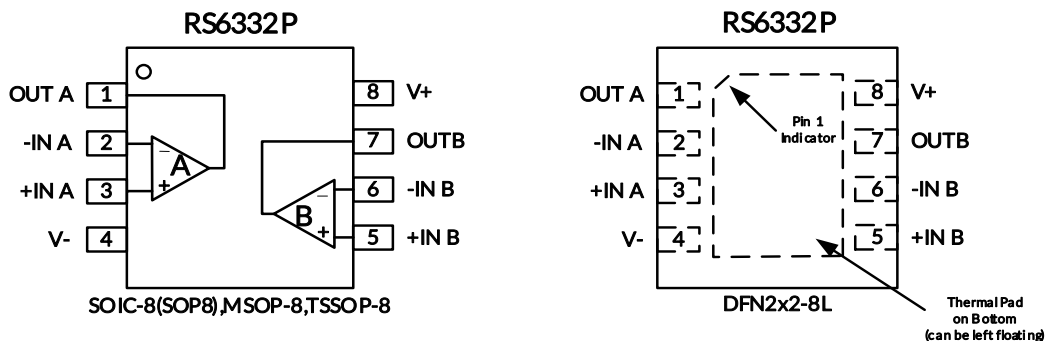


Pin Description

NAME	PIN			I/O ⁽¹⁾	DESCRIPTION
	RS6331P	RS6331BP	RS6331P		
	SOT23-5/SOT353 (SC70-5)	SOT23-5/SOT353 (SC70-5)	SOIC-8(SOP8)/MSOP8		
-IN	4	3	2	I	Negative (inverting) input
+IN	3	1	3	I	Positive (noninverting) input
NC ⁽²⁾	-	-	1,5,8	-	No internal connection (can be left floating)
OUT	1	4	6	O	Output
V-	2	2	4	-	Negative (lowest) power supply
V+	5	5	7	-	Positive (highest) power supply

(1) I = Input, O = Output.

(2) There is no internal connection. Typically, GND is the recommended connection to a heat spreading plane.

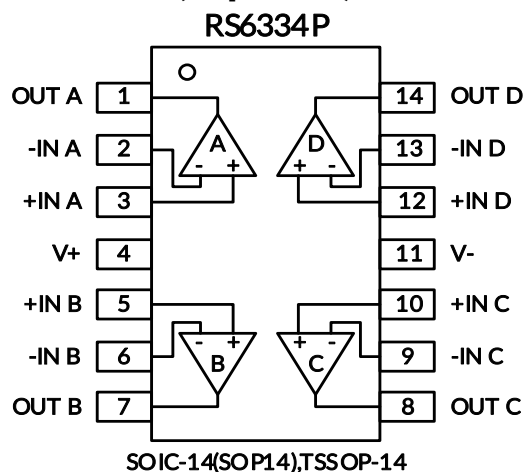


Pin Description

NAME	PIN		I/O ⁽¹⁾	DESCRIPTION
	SOIC-8(SOP8)/MSOP-8/TSSOP-8/DFN2x2-8L			
-INA	2		I	Inverting input, channel A
+INA	3		I	Noninverting input, channel A
-INB	6		I	Inverting input, channel B
+INB	5		I	Noninverting input, channel B
OUTA	1		O	Output, channel A
OUTB	7		O	Output, channel B
V-	4		-	Negative (lowest) power supply
V+	8		-	Positive (highest) power supply
-	Thermal Pad		-	Connect thermal pad to V-

(1) I = Input, O = Output.

Pin Configuration and Functions (Top View)



Pin Description

NAME	PIN	I/O ⁽¹⁾	DESCRIPTION
	SOIC-14(SOP14)/TSSOP-14		
-INA	2	I	Inverting input, channel A
+INA	3	I	Noninverting input, channel A
-INB	6	I	Inverting input, channel B
+INB	5	I	Noninverting input, channel B
-INC	9	I	Inverting input, channel C
+INC	10	I	Noninverting input, channel C
-IND	13	I	Inverting input, channel D
+IND	12	I	Noninverting input, channel D
OUTA	1	O	Output, channel A
OUTB	7	O	Output, channel B
OUTC	8	O	Output, channel C
OUTD	14	O	Output, channel D
V-	11	-	Negative (lowest) power supply
V+	4	-	Positive (highest) power supply

(1) I = Input, O = Output.

7 SPECIFICATIONS

7.1 Absolute Maximum Ratings

Over operating free-air temperature range (unless otherwise noted) ⁽¹⁾

		MIN	MAX	UNIT
Voltage	Supply, $V_S=(V+) - (V-)$		7	V
	Signal input pin ⁽²⁾	(V-)-0.5	(V+) +0.5	
	Signal output pin ⁽³⁾	(V-)-0.5	(V+) +0.5	
Current	Signal input pin ⁽²⁾	-10	10	mA
	Signal output pin ⁽³⁾	-150	150	mA
	Output short-circuits ⁽⁴⁾	Continuous		
θ_{JA}	Package thermal impedance ⁽⁵⁾	SOT23-5	230	°C/W
		SOIC-8(SOP8)	110.88	
		MSOP-8	165.7	
		TSSOP8	240	
		SOIC-14(SOP14)	104.5	
		TSSOP14	89.21	
		SOT353(SC70-5)	376	
TDFN2x2-8L	80			
Temperature	Operating range, T_A	-40	125	°C
	Junction, T_J ⁽⁶⁾	-40	150	
	Storage, T_{stg}	-65	150	

(1) Stresses above these ratings may cause permanent damage. Exposure to absolute maximum conditions for extended periods may degrade device reliability. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those specified is not implied.

(2) Input terminals are diode-clamped to the power-supply rails. Input signals that can swing more than 0.5V beyond the supply rails should be current-limited to 10mA or less.

(3) Output terminals are diode-clamped to the power-supply rails. Output signals that can swing more than 0.5V beyond the supply rails should be current-limited to ± 150 mA or less.

(4) Short-circuit to ground, one amplifier per package.

(5) The package thermal impedance is calculated in accordance with JE5D-51.

(6) The maximum power dissipation is a function of $T_{J(MAX)}$, $R_{\theta JA}$, and T_A . The maximum allowable power dissipation at any ambient temperature is $P_D = (T_{J(MAX)} - T_A) / R_{\theta JA}$. All numbers apply for packages soldered directly onto a PCB.

7.2 ESD Ratings

The following ESD information is provided for handling of ESD-sensitive devices in an ESD protected area only.

			VALUE	UNIT
$V_{(ESD)}$	Electrostatic discharge	Human-body model (HBM), per ANSI/ESDA/JEDEC JS-001 ⁽¹⁾	± 5000	V
		Charged-device model (CDM), per ANSI/ESDA/JEDEC JS-002 ⁽²⁾	± 1000	
		Machine Model (MM)	± 400	

(1) JEDEC document JEP155 states that 500 V HBM allows safe manufacturing with a standard ESD control process.

(2) JEDEC document JEP157 states that 250 V CDM allows safe manufacturing with a standard ESD control process.



ESD SENSITIVITY CAUTION

ESD damage can range from subtle performance degradation to complete device failure. Precision integrated circuits may be more susceptible to damage because very small parametric changes could cause the device not to meet its published specifications.

7.3 Recommended Operating Conditions

Over operating free-air temperature range (unless otherwise noted)

		MIN	NOM	MAX	UNIT
Supply voltage , $V_s = (V+) - (V-)$	Single-supply	2.2		5.5	V
	Dual-supply	±1.1		±2.75	

7.4 ELECTRICAL CHARACTERISTICS

(At $T_A = +25^\circ\text{C}$, $V_S = 2.2\text{V}$ to 5.5V , $R_L = 10\text{k}\Omega$ connected to $V_S/2$, and $V_{OUT} = V_S/2$, $V_{CM} = V_S/2$, Full ⁽⁹⁾ = -40°C to $+125^\circ\text{C}$, unless otherwise noted.)⁽¹⁾

PARAMETER		CONDITIONS	T_J	RS6331P, RS6332P, RS6334P			
				MIN ⁽²⁾	TYP ⁽³⁾	MAX ⁽²⁾	UNIT
POWER SUPPLY							
V_S	Operating Voltage Range		25°C	2.2		5.5	V
I_Q	Quiescent Current Per Amplifier	$V_S = \pm 2.5\text{V}$, $I_O = 0\text{mA}$	25°C		62.5	100	μA
PSRR	Power-Supply Rejection Ratio	$V_S = 2.2\text{V}$ to 5.5V	25°C	75	92		dB
			Full	65			
INPUT							
V_{OS}	Input Offset Voltage	$V_{CM} = V_S/2$	25°C	-0.8	± 0.1	0.8	mV
$V_{OS\ TC}$	Input Offset Voltage Average Drift	$V_{CM} = V_S/2$	Full		± 1		$\mu\text{V}/^\circ\text{C}$
I_B	Input Bias Current ^{(4) (5)}	$V_{CM} = 0\text{V}$	25°C		± 1	± 10	μA
I_{OS}	Input Offset Current ⁽⁵⁾	$V_{CM} = 0\text{V}$	25°C		± 1	± 10	μA
V_{CM}	Common-Mode Voltage Range	$V_S = 5.5\text{V}$	25°C	-0.1		5.6	V
CMRR	Common-Mode Rejection Ratio	$V_S = 5.5\text{V}$ $V_{CM} = -0.1\text{V}$ to 3.5V	25°C	74	93		dB
			Full	63			
		$V_S = 5.5\text{V}$ $V_{CM} = -0.1\text{V}$ to 5.6V	25°C	60	77		
			Full	59			
OUTPUT							
A_{OL}	Open-Loop Voltage Gain	$R_L = 10\text{k}\Omega$, $V_O = (V_-) + 0.1\text{V}$ to $(V_+) - 0.1\text{V}$	25°C	110	122		dB
			Full	87			
	Output Swing From Rail	$V_S = \pm 2.5\text{V}$, $R_L = 10\text{k}\Omega$	25°C		10	20	mV
I_{OUT}	Output Short-Circuit Current ^{(6) (7)}		25°C	± 60	± 96		mA
C_{LOAD}	Capacitive Load Drive				100		pF
FREQUENCY RESPONSE							
SR	Slew Rate ⁽⁸⁾	$G = +1$, $C_L = 100\text{pF}$	25°C		0.5		V/ μs
GBP	Gain-Bandwidth Product		25°C		1.4		MHz
PM	Phase Margin ⁽⁵⁾		25°C		64		$^\circ$
t_s	Settling Time, 0.1%	$V_S = \pm 2.5\text{V}$, $G = +1$, $C_L = 100\text{pF}$, Step = 2V	25°C		6.5		μs
t_{OR}	Overload Recovery Time	$V_{IN} \cdot \text{Gain} \geq V_S$, $G = -10$	25°C		5.3		μs
NOISE							
E_n	Input Voltage Noise	$f = 0.1\text{Hz}$ to 10Hz , $V_S = \pm 2.5\text{V}$	25°C		4.5		μV_{PP}
e_n	Input Voltage Noise Density	$f = 1\text{KHz}$	25°C		TBD		$\text{nV}/\sqrt{\text{Hz}}$

NOTE:

- (1) Electrical table values apply only for factory testing conditions at the temperature indicated. Factory testing conditions result in very limited self-heating of the device.
- (2) Limits are 100% production tested at 25°C. Limits over the operating temperature range are ensured through correlations using statistical quality control (SQC) method.
- (3) Typical values represent the most likely parametric norm as determined at the time of characterization. Actual typical values may vary over time and will also depend on the application and configuration.
- (4) Positive current corresponds to current flowing into the device.
- (5) This parameter is ensured by design and/or characterization and is not tested in production.
- (6) The maximum power dissipation is a function of $T_{J(MAX)}$, $R_{\theta JA}$, and T_A . The maximum allowable power dissipation at any ambient temperature is $PD = (T_{J(MAX)} - T_A) / R_{\theta JA}$. All numbers apply for packages soldered directly onto a PCB.
- (7) Short circuit test is a momentary test.
- (8) Number specified is the slower of positive and negative slew rates.
- (9) Specified by characterization only.

7.5 TYPICAL CHARACTERISTICS

NOTE: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only.

At $T_A = +25^\circ\text{C}$, $V_S = 5\text{V}$, $R_L = 10\text{k}\Omega$ connected to $V_S/2$, $V_{OUT} = V_S/2$, unless otherwise noted.

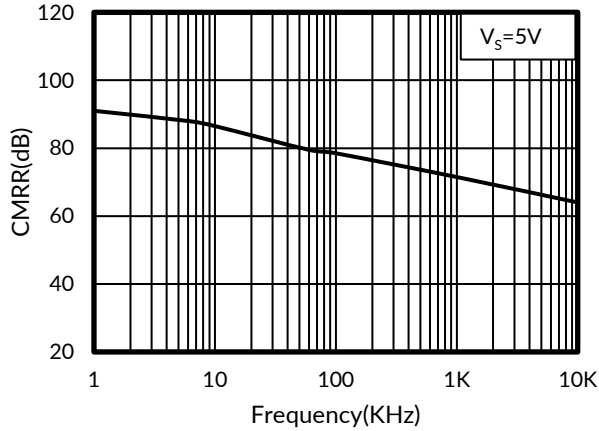


Figure 1. Common-mode Rejection Ratio vs Frequency

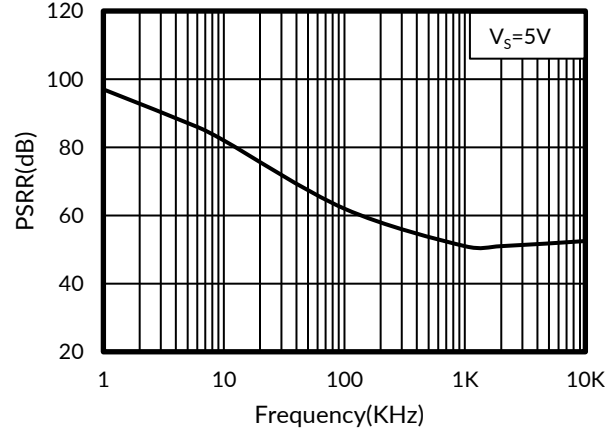


Figure 2. Power-Supply Rejection Ratio vs Frequency

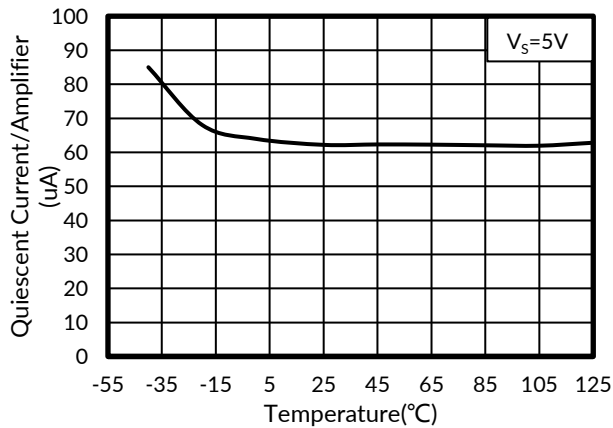


Figure 3. Quiescent Current vs Temperature

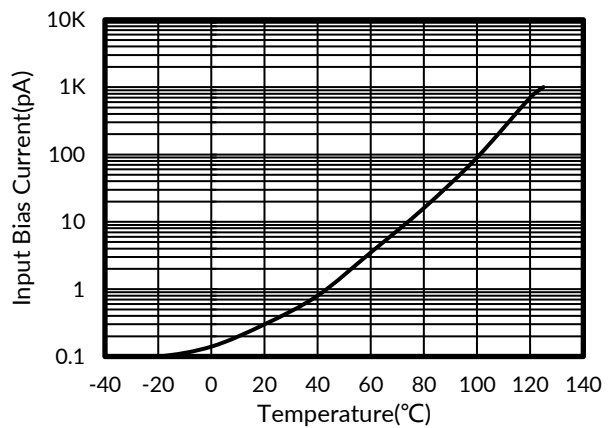


Figure 4. Input Bias Current vs Temperature

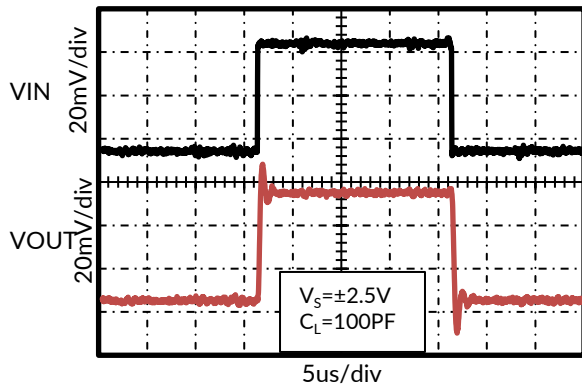


Figure 5. Small-Signal Step Response

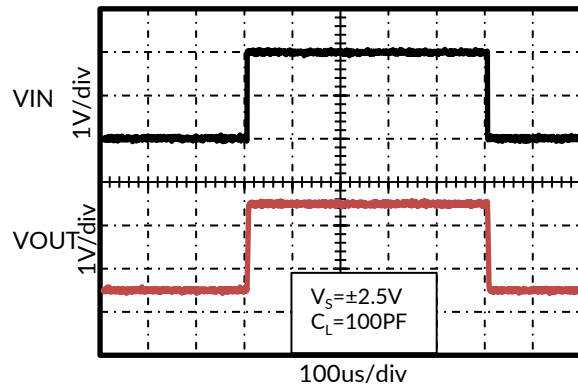


Figure 6. Large-Signal Step Response

TYPICAL CHARACTERISTICS

NOTE: The graphs and tables provided following this note are a statistical summary based on a limited number of samples and are provided for informational purposes only.

At $T_A = +25^\circ\text{C}$, $V_S = 5\text{V}$, $R_L = 10\text{k}\Omega$ connected to $V_S/2$, $V_{OUT} = V_S/2$, unless otherwise noted.

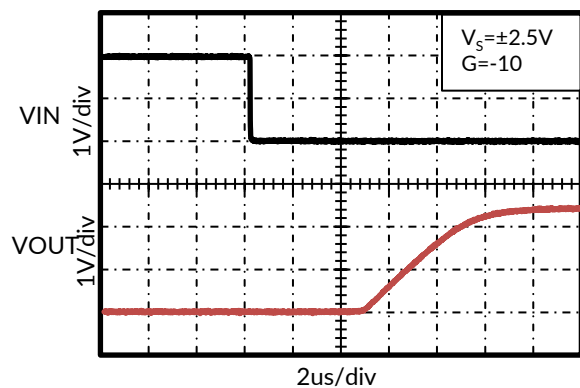


Figure 7. Negative Overvoltage Recovery

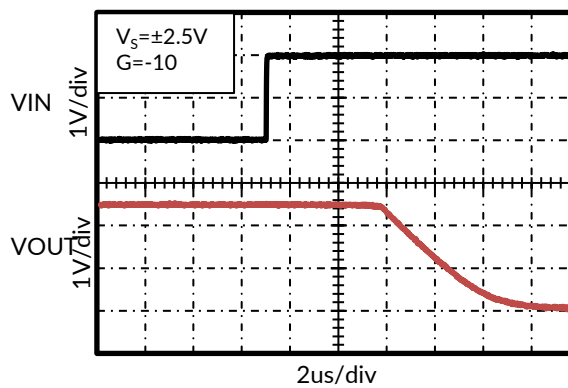


Figure 8. Positive Overvoltage Recovery

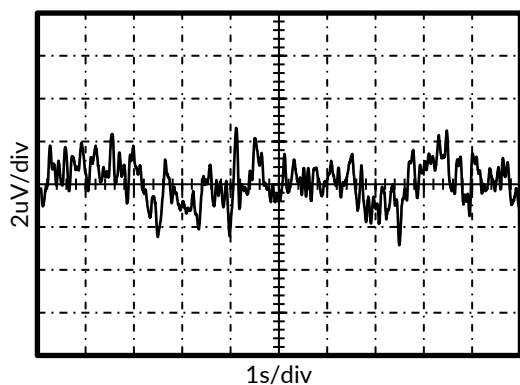


Figure 9. 0.1Hz to 10Hz Input Voltage Noise

8 Application and Implementation

Information in the following applications sections is not part of the Runic component specification, and Runic does not warrant its accuracy or completeness. Runic's customers are responsible for determining suitability of components for their purposes. Customers should validate and test their design implementation to confirm system functionality.

8.1 APPLICATION NOTES

The RS6331P, RS6332P, RS6334P are high precision, rail-to-rail operational amplifiers that can be run from a single-supply voltage 2.2V to 5.5V ($\pm 1.1V$ to $\pm 2.75V$). Supply voltages higher than 7V (absolute maximum) can permanently damage the amplifier. Rail-to-rail input and output swing significantly increases dynamic range, especially in low-supply applications. Good layout practice mandates use of a 0.1 μ F capacitor placed closely across the supply pins.

8.2 LAYOUT GUIDELINS

Attention to good layout practices is always recommended. Keep traces short. When possible, use a PCB ground plane with surface-mount components placed as close to the device pins as possible. Place a 0.1 μ F capacitor closely across the supply pins. These guidelines should be applied throughout the analog circuit to improve performance and provide benefits such as reducing the EMI susceptibility.

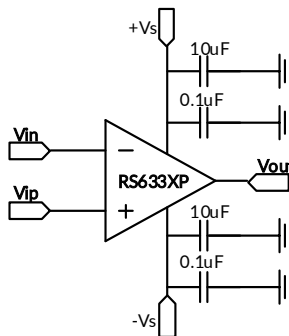


Figure 10. Amplifier with Bypass Capacitors

8.3 INSTRUMENTATION AMPLIFIER

In the three-op amp, instrumentation amplifier configuration shown in Figure 11.

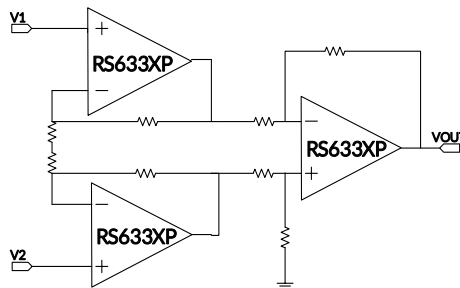
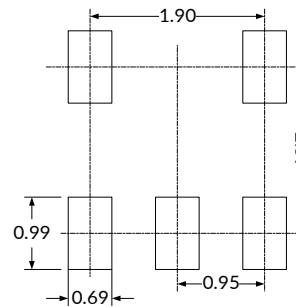
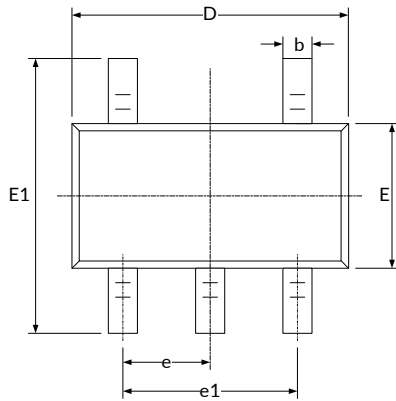


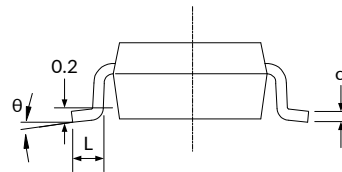
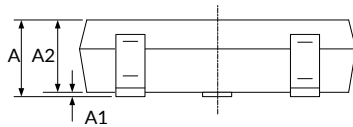
Figure 11. Amplifier instrumentation amplifier

9 PACKAGE OUTLINE DIMENSIONS

SOT23-5⁽³⁾



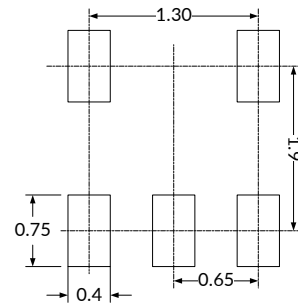
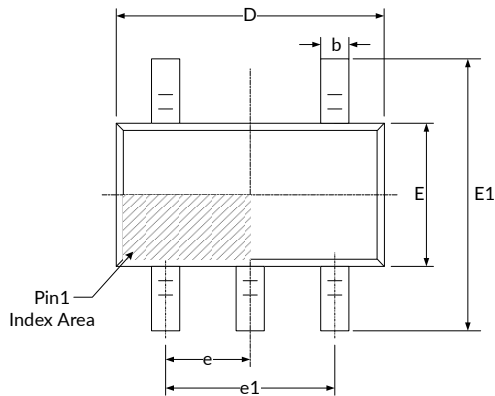
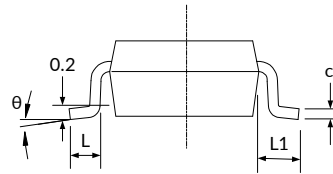
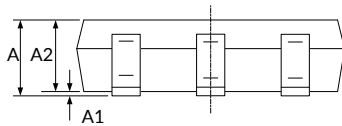
RECOMMENDED LAND PATTERN (Unit: mm)



Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A ⁽¹⁾	1.050	1.250	0.041	0.049
A1	0.000	0.100	0.000	0.004
A2	1.050	1.150	0.041	0.045
b	0.300	0.500	0.012	0.020
c	0.100	0.200	0.004	0.008
D ⁽¹⁾	2.820	3.020	0.111	0.119
E ⁽¹⁾	1.500	1.700	0.059	0.067
E1	2.650	2.950	0.104	0.116
e	0.950(BSC) ⁽²⁾		0.037(BSC) ⁽²⁾	
e1	1.800	2.000	0.071	0.079
L	0.300	0.600	0.012	0.024
θ	0°	8°	0°	8°

NOTE:

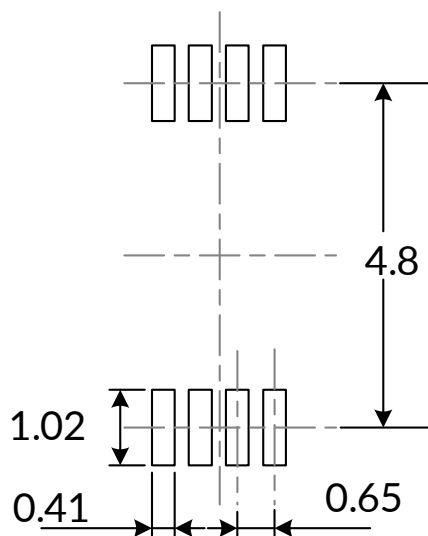
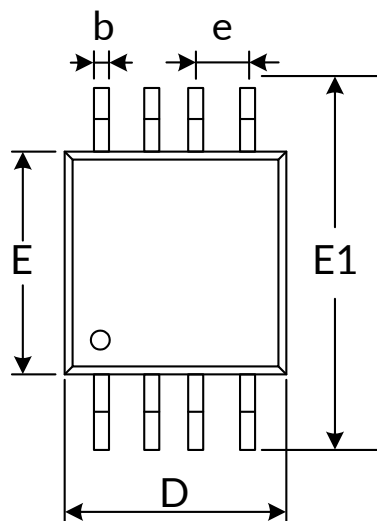
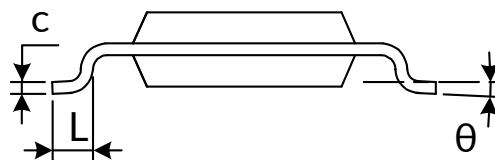
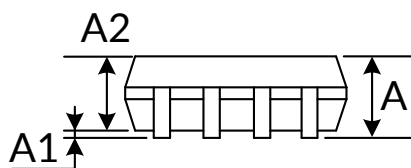
1. Plastic or metal protrusions of 0.15mm maximum per side are not included.
2. BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
3. This drawing is subject to change without notice.

SOT353(SC70-5)⁽³⁾

RECOMMENDED LAND PATTERN (Unit: mm)


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A ⁽¹⁾	0.900	1.100	0.035	0.043
A1	0.000	0.100	0.000	0.004
A2	0.900	1.000	0.035	0.039
b	0.150	0.350	0.006	0.014
c	0.080	0.150	0.003	0.006
D ⁽¹⁾	2.000	2.200	0.079	0.087
E ⁽¹⁾	1.150	1.350	0.045	0.053
E1	2.150	2.450	0.085	0.096
e	0.650(BSC) ⁽²⁾		0.026(BSC) ⁽²⁾	
e1	1.300(BSC) ⁽²⁾		0.051(BSC) ⁽²⁾	
L	0.260	0.460	0.010	0.018
L1	0.525		0.021	
θ	0°	8°	0°	8°

NOTE:

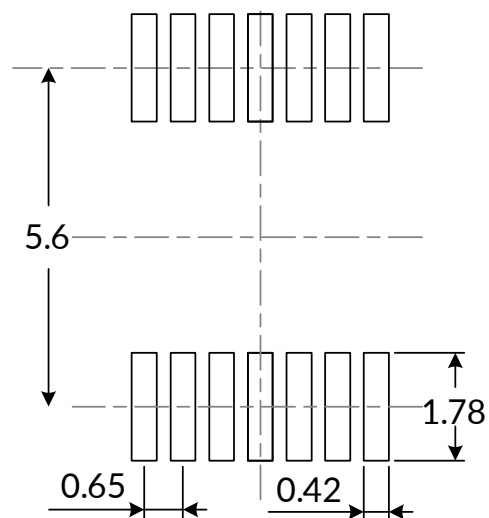
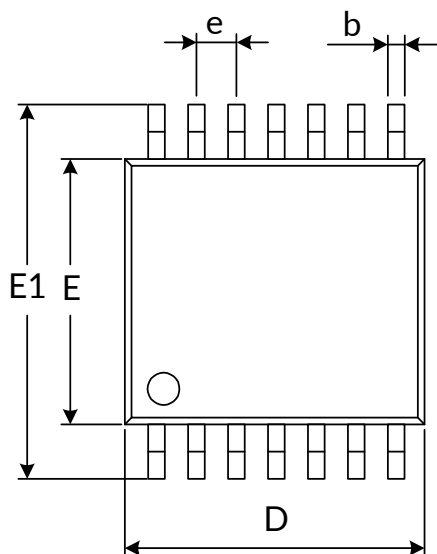
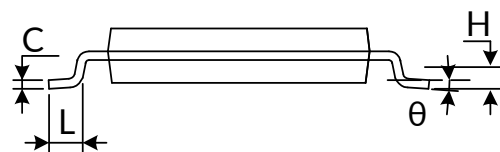
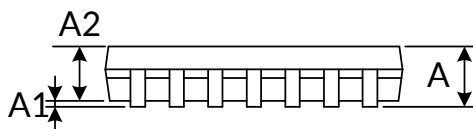
1. Plastic or metal protrusions of 0.15mm maximum per side are not included.
2. BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
3. This drawing is subject to change without notice.

MSOP-8⁽³⁾

RECOMMENDED LAND PATTERN (Unit: mm)


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A ⁽¹⁾	0.820	1.100	0.032	0.043
A1	0.020	0.150	0.001	0.006
A2	0.750	0.950	0.030	0.037
b	0.250	0.380	0.010	0.015
c	0.090	0.230	0.004	0.009
D ⁽¹⁾	2.900	3.100	0.114	0.122
e	0.650(BSC) ⁽²⁾		0.026(BSC) ⁽²⁾	
E ⁽¹⁾	2.900	3.100	0.114	0.122
E1	4.750	5.050	0.187	0.199
L	0.400	0.800	0.016	0.031
θ	0°	6°	0°	6°

NOTE:

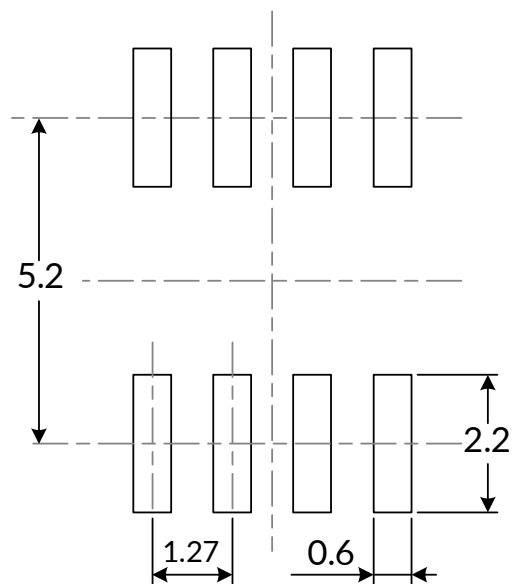
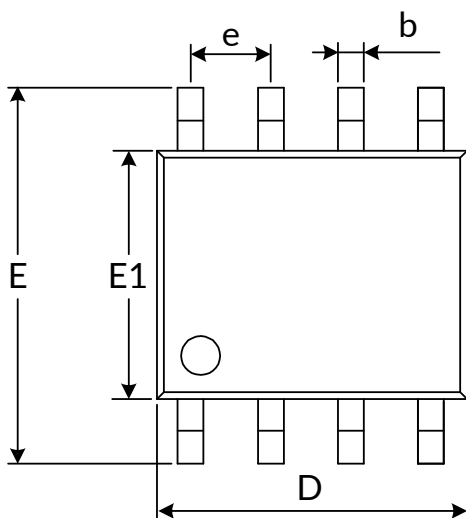
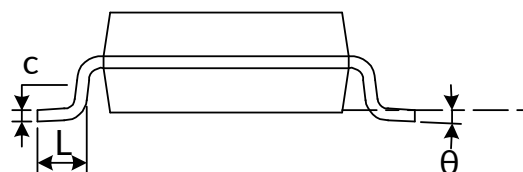
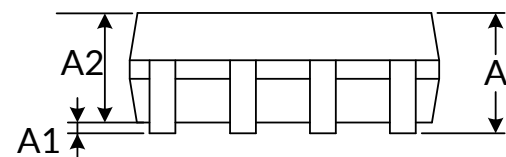
1. Plastic or metal protrusions of 0.15mm maximum per side are not included.
2. BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
3. This drawing is subject to change without notice.

TSSOP-14 (3)

RECOMMENDED LAND PATTERN (Unit: mm)


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A ⁽¹⁾		1.200		0.047
A1	0.050	0.150	0.002	0.006
A2	0.800	1.050	0.031	0.041
b	0.190	0.300	0.007	0.012
c	0.090	0.200	0.004	0.008
D ⁽¹⁾	4.860	5.100	0.191	0.201
E ⁽¹⁾	4.300	4.500	0.169	0.177
E1	6.250	6.550	0.246	0.258
e	0.650(BSC) ⁽²⁾		0.026(BSC) ⁽²⁾	
L	0.500	0.700	0.020	0.028
H	0.25(TYP)		0.01(TYP)	
θ	1°	7°	1°	7°

NOTE:

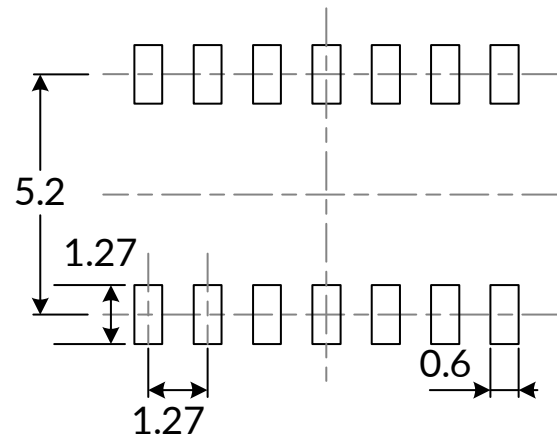
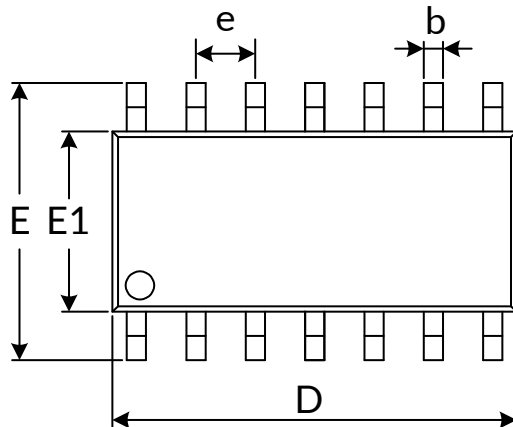
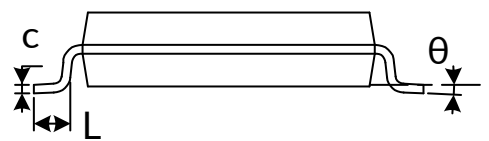
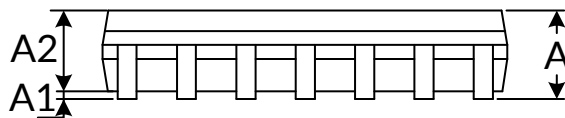
1. Plastic or metal protrusions of 0.15mm maximum per side are not included.
2. BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
3. This drawing is subject to change without notice.

SOIC-8(SOP8) ⁽³⁾

RECOMMENDED LAND PATTERN (Unit: mm)


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A ⁽¹⁾	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.330	0.510	0.013	0.020
c	0.170	0.250	0.007	0.010
D ⁽¹⁾	4.800	5.000	0.189	0.197
e	1.270(BSC) ⁽²⁾		0.050(BSC) ⁽²⁾	
E	5.800	6.200	0.228	0.244
E1 ⁽¹⁾	3.800	4.000	0.150	0.157
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

NOTE:

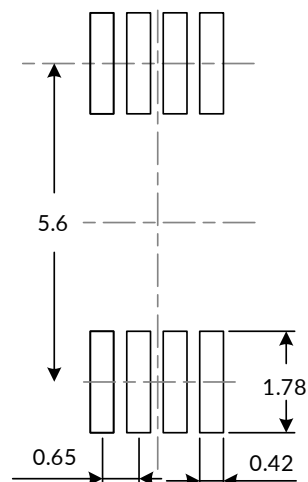
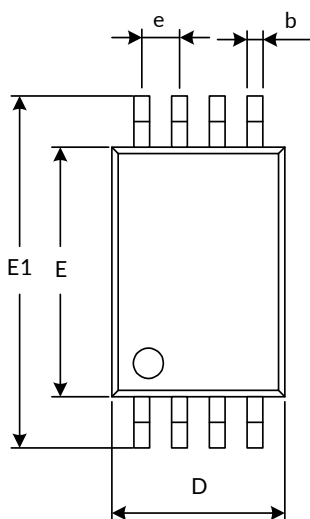
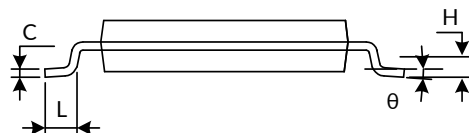
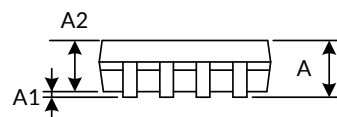
1. Plastic or metal protrusions of 0.15mm maximum per side are not included.
2. BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
3. This drawing is subject to change without notice.

SOIC-14(SOP14)⁽³⁾

RECOMMENDED LAND PATTERN (Unit: mm)


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A ⁽¹⁾	1.350	1.750	0.053	0.069
A1	0.100	0.250	0.004	0.010
A2	1.350	1.550	0.053	0.061
b	0.310	0.510	0.012	0.020
c	0.100	0.250	0.004	0.010
D ⁽¹⁾	8.450	8.850	0.333	0.348
e	1.270(BSC) ⁽²⁾		0.050(BSC) ⁽²⁾	
E	5.800	6.200	0.228	0.244
E1 ⁽¹⁾	3.800	4.000	0.150	0.157
L	0.400	1.270	0.016	0.050
θ	0°	8°	0°	8°

NOTE:

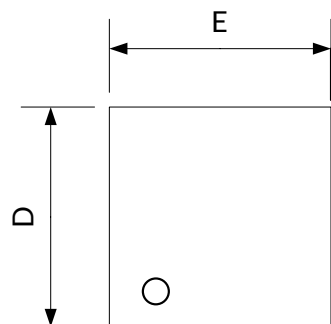
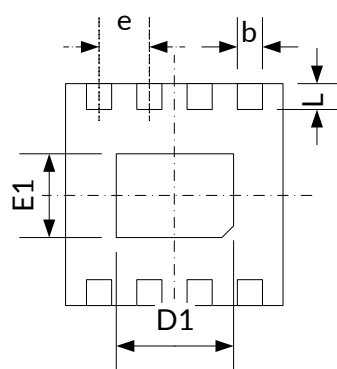
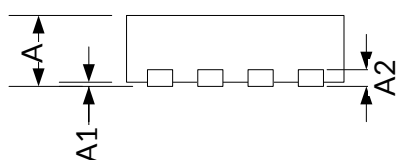
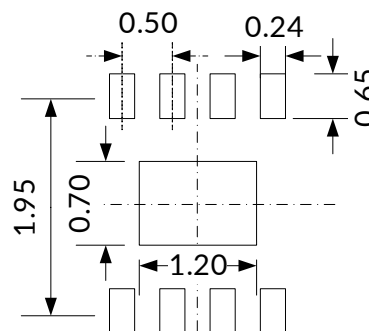
1. Plastic or metal protrusions of 0.15mm maximum per side are not included.
2. BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
3. This drawing is subject to change without notice.

TSSOP-8⁽³⁾

RECOMMENDED LAND PATTERN (Unit: mm)


Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A ⁽¹⁾		1.200		0.047
A1	0.050	0.150	0.002	0.006
A2	0.800	1.050	0.031	0.041
b	0.190	0.300	0.007	0.012
c	0.090	0.200	0.004	0.008
D ⁽¹⁾	2.900	3.100	0.114	0.122
E ⁽¹⁾	4.300	4.500	0.169	0.177
E1	6.250	6.550	0.246	0.258
e	0.650(BSC) ⁽²⁾		0.026(BSC) ⁽²⁾	
L	0.500	0.700	0.020	0.028
H	0.25(TYP)		0.01(TYP)	
θ	1°	7°	1°	7°

NOTE:

1. Plastic or metal protrusions of 0.15mm maximum per side are not included.
2. BSC (Basic Spacing between Centers), "Basic" spacing is nominal.
3. This drawing is subject to change without notice.

DFN-2x2-8L⁽²⁾

TOP VIEW

BOTTOM VIEW

SIDE VIEW

RECOMMENDED LAND PATTERN (Unit: mm)

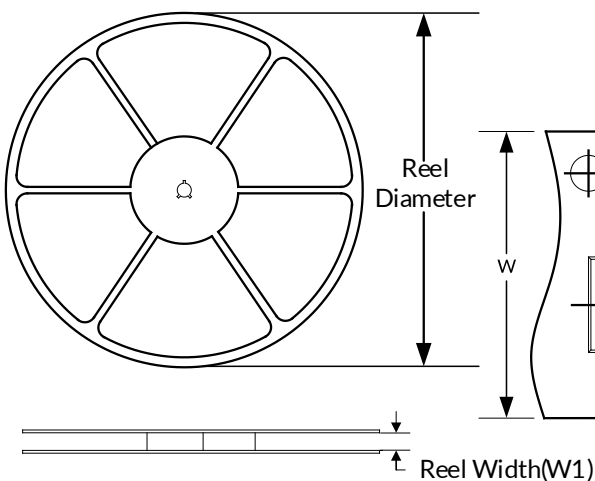
Symbol	Dimensions In Millimeters		Dimensions In Inches	
	Min	Max	Min	Max
A ⁽¹⁾	0.700	0.800	0.028	0.031
A1	0.000	0.050	0.000	0.002
A2	0.203(TYP)		0.008(TYP)	
b	0.180	0.300	0.007	0.012
D ⁽¹⁾	1.900	2.100	0.075	0.083
D1	1.100	1.300	0.043	0.051
E ⁽¹⁾	1.900	2.100	0.075	0.083
E1	0.600	0.800	0.024	0.031
e	0.500(TYP)		0.020(TYP)	
L	0.250	0.450	0.010	0.018

NOTE:

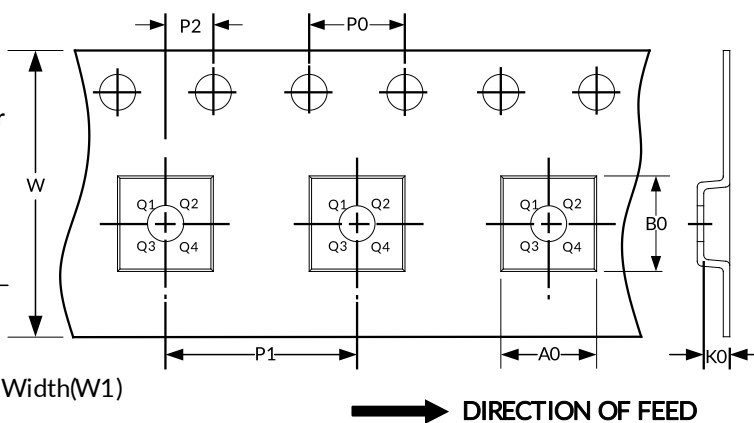
1. Plastic or metal protrusions of 0.075mm maximum per side are not included.
2. This drawing is subject to change without notice.

10 TAPE AND REEL INFORMATION

REEL DIMENSIONS



TAPE DIMENSION



NOTE: The picture is only for reference. Please make the object as the standard.

KEY PARAMETER LIST OF TAPE AND REEL

Package Type	Reel Diameter	Reel Width (mm)	A0 (mm)	B0 (mm)	K0 (mm)	P0 (mm)	P1 (mm)	P2 (mm)	W (mm)	Pin1 Quadrant
SOT23-5	7"	9.5	3.20	3.20	1.40	4.0	4.0	2.0	8.0	Q3
SOT353(SC70-5)	7"	9.5	2.25	2.55	1.20	4.0	4.0	2.0	8.0	Q3
MSOP-8	13"	12.4	5.20	3.30	1.50	4.0	8.0	2.0	12.0	Q1
SOIC-8(SOP8)	13"	12.4	6.40	5.40	2.10	4.0	8.0	2.0	12.0	Q1
DFN2X2-8L	7"	9.5	2.30	2.30	1.10	4.0	4.0	2.0	8.0	Q2
TSSOP-14	13"	12.4	6.95	5.60	1.20	4.0	8.0	2.0	12.0	Q1
SOIC-14(SOP14)	13"	16.4	6.60	9.30	2.10	4.0	8.0	2.0	16.0	Q1

NOTE:

1. All dimensions are nominal.
2. Plastic or metal protrusions of 0.15mm maximum per side are not included.

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